

BB02-EA :- 1.27mm x 2.54mm (0.05" x 0.1") SOCKET, DUAL ROW, STRAIGHT, THROUGH HOLE, 6 - 100 CONTACTS

SPECIFICATIONS

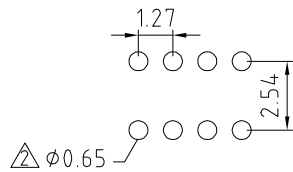
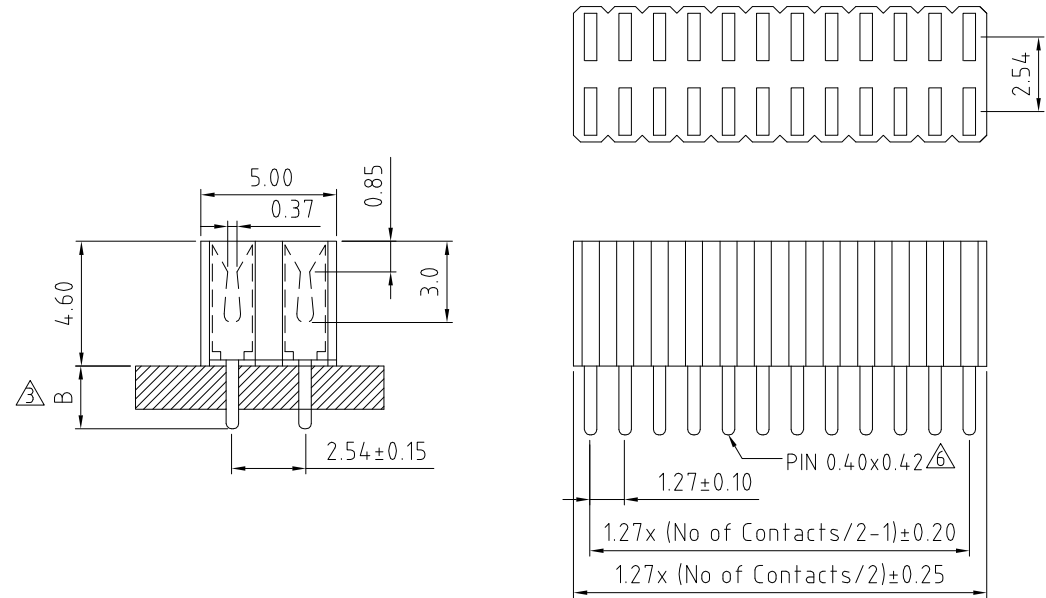
CURRENT RATING 1 AMP  
 INSULATOR RESISTANCE 1000 MEGOHMS MIN.  
 CONTACT RESISTANCE 20m ohms MAX.  
 DIELECTRIC WITHSTANDING AC 300 V  
 OPERATING TEMPERATURE -40°C TO +105°C  
 CONTACT MATERIAL PHOSPHOR BRONZE  
 INSULATOR MATERIAL THERMOPLASTIC, UL 94V-0  
 STANDARD: LCP + 30% G/F  
 PLATING GOLD OR TIN OVER 30-50U" NICKEL  
 SOLDERABILITY IR REFLOW: 280°C FOR 10 SEC  
 WAVE: 250°C FOR 5-10 SEC  
 MANUAL SOLDER: 380°C FOR 3-5 SEC

PACKED IN TUBE OR TRAY.

NOTES:

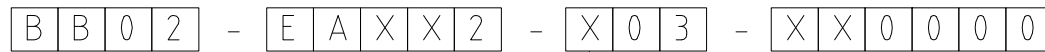
1. RECOMMENDED MATING PIN LENGTH: 2.5MM.  $\Delta$

MATES WITH :- BB02-DA  
 BB02-DE  
 BB02-DF  
 BB02-DG



RECOMMENDED PC BOARD HOLE LAYOUT  
 (TOLERANCE: ±0.05)

HOW TO ORDER



NO. OF CONTACTS  
 06 TO 98  
 100 Contacts = 00

CONTACT PLATING OPTIONS  
 K = GOLD FLASH (STANDARD)  
 A = 10U" GOLD ON CONTACT/GOLD FLASH ON TAIL  
 B = 15U" GOLD ON CONTACT/GOLD FLASH ON TAIL  
 C = 30U" GOLD ON CONTACT/GOLD FLASH ON TAIL  
 T = BRIGHT TIN  
 M = MATT TIN

PIN LENGTH B  $\Delta$   
 15 = 1.5 MM  
 24 = 2.4 MM (STANDARD)  
 30 = 3.0 MM  
 TOL. ±0.20mm

10	28/05/03 - NIR RELEASE
11	12/02/05 - NYW DRAWING MODIFICATION
12	21/07/05 - NYW AHEAD PIN LENGTH, AHEAD PCB LAYOUT.
13	11/11/05 - NYW AHEAD PIN LENGTH OPTION.
14	24/07/06 - NYW DRAWING MODIFICATION.
15	12/09/07 - NYW ADD NOTES 1.
16	18/01/08 - NYW PLATING MODIFICATION.
17	21/05/08 - NYW ADD MATT TIN PLATING.
18	30/12/08 - CHC DRAWING MODIFICATION.
19	20/05/11 - NYW CHANGE INSULATOR TO LCP.

Scale:	5:1
Drawn:	CHC
App'd:	XXXX
Date:	20 MAY '11

THIRD ANGLE	
Title	SOCKET
Revision:	1.9

Unstated Tolerances:	X: ± 0.30 X: ± 0.25 .XX: ± 0.15 .XXX: ± 0.10
Material	SEE NOTE
UNIT:	mm

Material	SEE NOTE
NOT TO SCALE	

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Type:	BB02-EA
Drawing Number:	BB02-EA
Sheet 1 of 1	
Drawing	E and O E